

100V N-CHANNEL ENHANCEMENT MODE MOSFET

MAIN CHARACTERISTICS

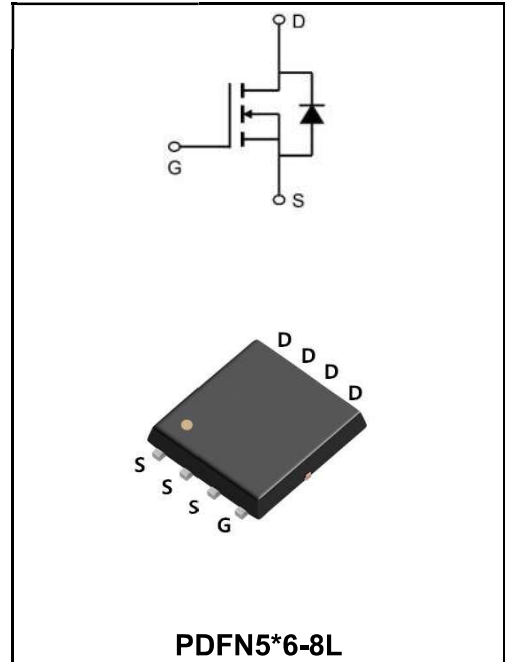
I_D	60A
V_{DSS}	100V
R_{DS(on)-typ(@V_{GS}=10V)}	< 12mΩ (Type:9.0 mΩ)

Features

◆ YFW-SGT technology

Application

- ◆ Isolated DC
- ◆ Motor control
- ◆ Synchronous-rectification



Product Specification Classification

Part Number	Package	Marking	Pack
YFWG60N10NF	PDFN5*6-8L	YFW 60N10NF XXXXX	5000PCS/Tape

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	100	V
Gate - Source Voltage	V_{GS}	±20	V
Continuous drain current ¹⁾ , T _c =25 °C	I_D	60	A
Pulsed drain current ²⁾ , T _c =25 °C	I_{DM}	180	A
Power dissipation ³⁾ , T _c =25 °C	P_D	107	W
Single Pulse Avalanche Energy ⁴⁾	E_{AS}	183.8	mJ
Operation and storage temperature	T_{STG}, T_J	-55 to +150	°C
Thermal Resistance, Junction-case	R_{θJC}	1.17	°C/W
Thermal Resistance, Junction-ambient ⁴⁾	R_{θJA}	62	°C/W

Maximum Ratings at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	BV_{DSS}	100	111	-	V
Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	$V_{GS(th)}$	1.2	1.8	2.5	V
Drain-source on-state resistance	$V_{GS}=10V, I_D=20A$	$R_{DS(on)}$	-	9.0	12.0	mΩ
	$V_{GS}=4.5V, I_D=12A$		-	12	14.0	
Gate-Source Leakage Current	$V_{GS}=\pm 20V$	I_{GSS}	-	-	± 100	nA
Drain-Source Leakage Current	$V_{DS}=100V, V_{GS}=0V$	I_{DSS}	-	-	1	μA
Gate resistance	f= 1 MHz, Open drain	R_G	-	5.5		Ω
Input Capacitance	$V_{GS}=0V$ $V_{DS}=50V$ f=100KHz	C_{iss}	-	1998.1	-	pF
Output Capacitance		C_{oss}	-	321.7	-	
Reverse Transfer Capacitance		C_{rss}	-	7.1	-	
Turn-on delay time	$V_{GS}=10V$ $V_{DS}=50V$ $R_G=2\Omega$ $I_D=25A$	$t_{d(on)}$	-	22.1	-	ns
Rise Time		T_r	-	5.2	-	
Turn-Off Delay Time		$t_{d(OFF)}$	-	44	-	
Fall Time		t_f	-	8.4	-	
Total Gate Charge	$I_D=25A$ $V_{DS}=50V$ $V_{GS}=10V$	Q_g	-	28.9	-	nC
Gate-Source Charge		Q_{gs}	-	6	-	
Gate-Drain Charge		Q_{gd}	-	6.8	-	
Gate plateau voltage		$V_{plateau}$	-	3.7	-	
Diode forward current	$V_{GS}<V_{th}$	I_S	-	-	60	A
Pulsed Source Current		I_{SP}	-	-	180	
Diode Forward Voltage	$I_S=20A, V_{GS}=0V$	V_{SD}	-	-	1.3	V
Reverse Recovery Time	$I_S=25A, di/dt=100A/\mu s$	t_{rr}	-	102.9	-	ns
Reverse Recovery Charge		Q_{rr}	-	379	-	nC
Peak reverse recovery current		I_{rrm}	-	6.4	-	A

Note :

- 1、 The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、 The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3、 The EAS data shows Max. rating . The test condition is $V_{DD}=30V, V_{GS}=10V, L=0.3mH$, starting $T_j=25^\circ C$
- 4、 The power dissipation is limited by $150^\circ C$ junction temperature
- 5、 The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation

Typical Characteristics

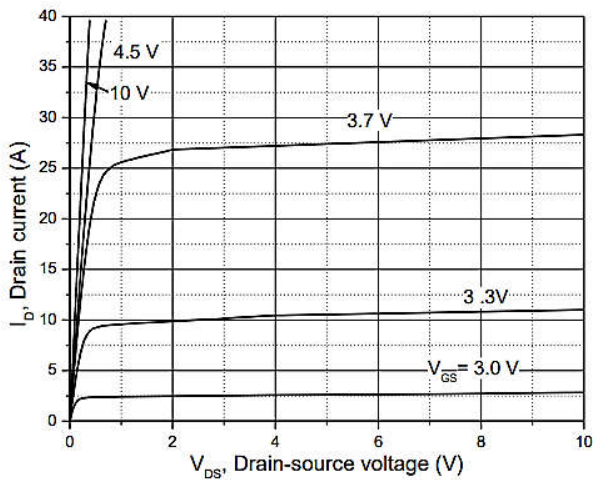


Figure 1. Typ. output characteristics

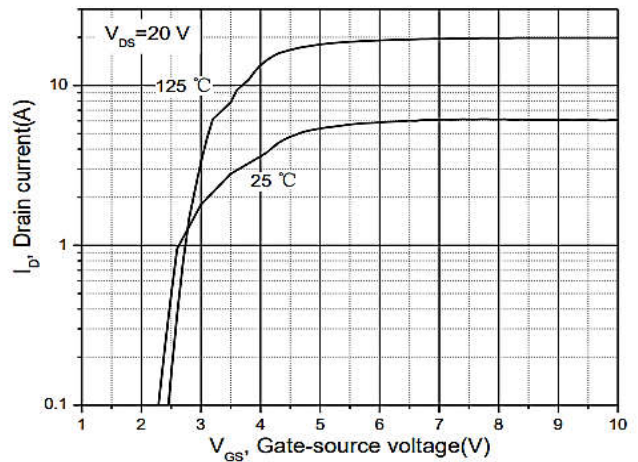


Figure 2. Typ. transfer characteristics

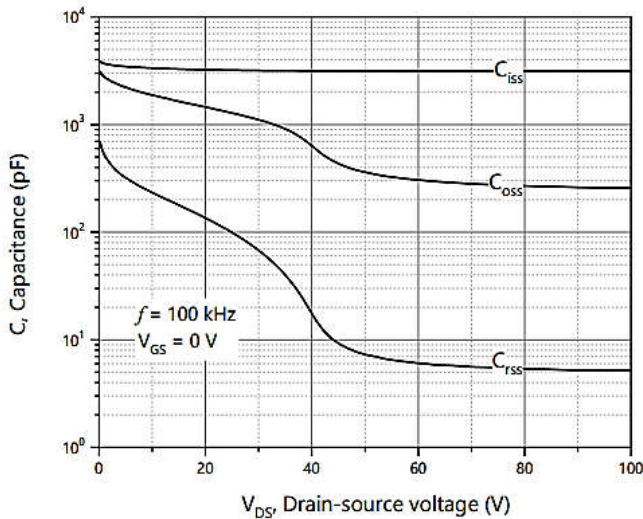


Figure 3. Typ. capacitances

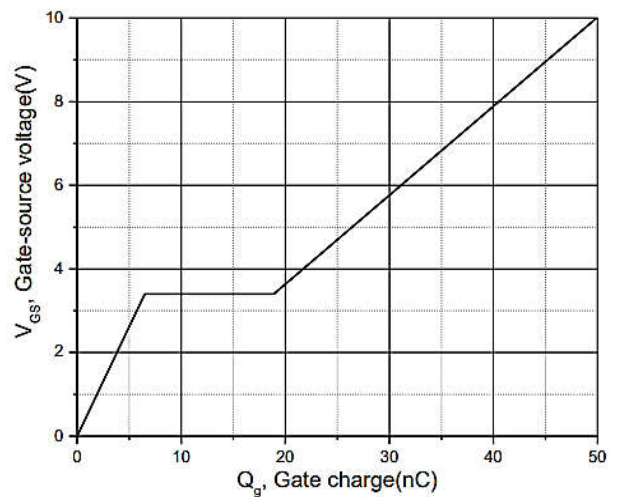


Figure 4. Typ. gate charge

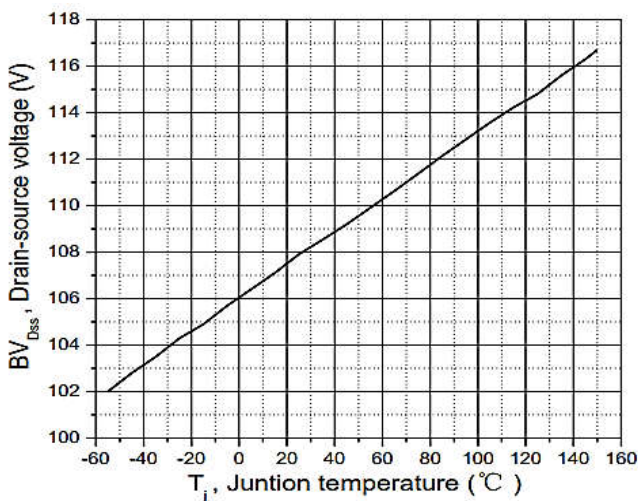


Figure 5. Drain-source breakdown voltage

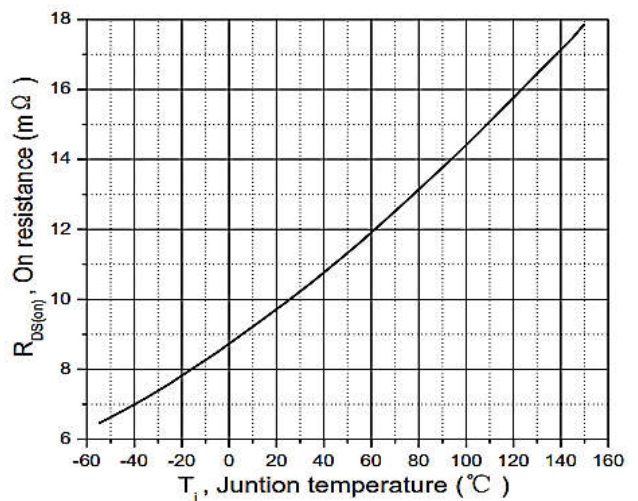


Figure 6. Drain-source on-state resistance

Ratings and Characteristic Curves

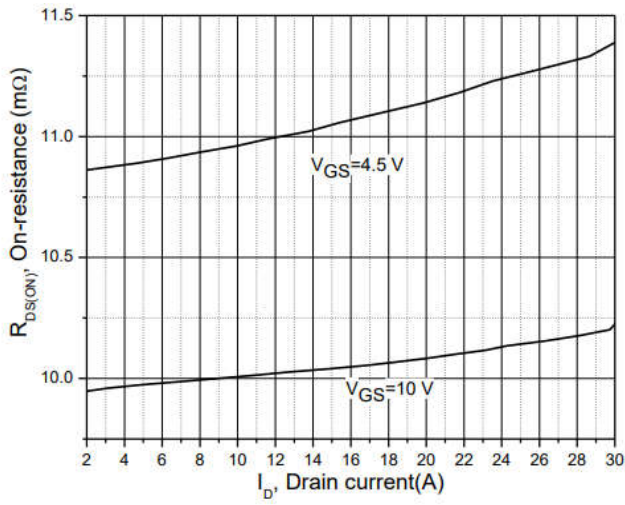


Figure 7. Drain-source on-state resistance

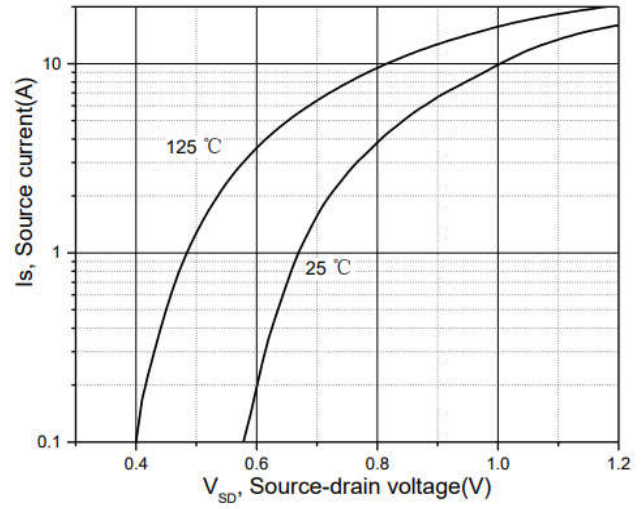


Figure 8. Forward characteristic of body diode

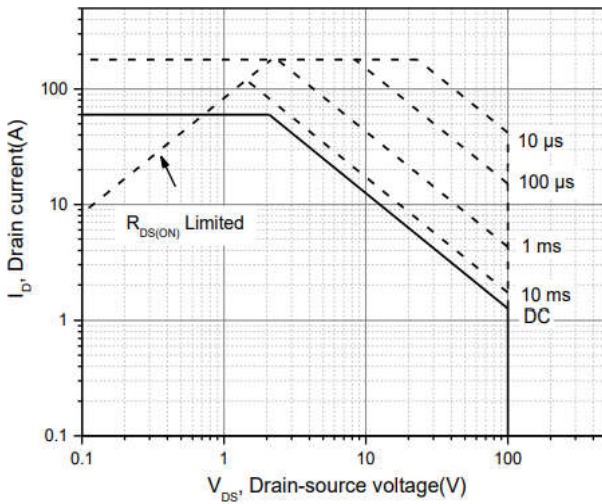
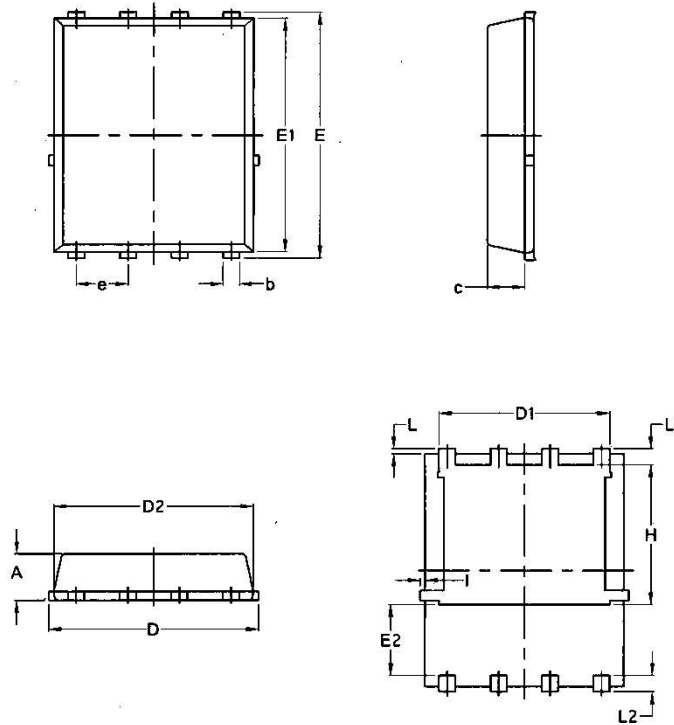


Figure 9. Safe operation area $T_c=25\text{ °C}$

PDFN5*6-8L



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070